

KIOXIA Corporation

2-5-1, Kasama, Sakae-ku, Yokohama, 247-8585 Japan
 PHONE: 81-45-890-2538
 Date: July 14th, 2021
 Ref. No.: 21MQ-G004-1(E)

To: _____

Product Change Notification

This letter is to inform you of the following changes.

1. Affected products

Product type: 24nm 4Gbit 2-stack SLC NAND/BENAND™ TSOP-packaged products
 Part number: TH58NVG3S0HTA00, TH58NVG3S0HTA10, TH58BVG3S0HTA00, TH58BVG3S0HTA10

2. Reason for change

The production of the current lead frame will be discontinued due to end-of life (EOL).

3. Change description

The supplier of the lead frame will be changed.
 Due to this change, the lead frame processing method will be also changed from etching to stamping.
 The changed lead frame has been used in other products.
 Due to the supplier and lead frame processing method change, the composition ratio of the mold resin will be adjusted.
 There is no change of structure and the specification of the products.

4. Change schedule

Production using the changed lead frame is targeted to start from January 2022 (running change).

5. Reliability data

Moisture Resistance Test (MRT), Highly Accelerated Stress Test (HAST) and Temperature Cycling (TC) results showed no failures. For reliability test data, please see the attached file.

6. Evaluation samples

Evaluation samples are available.
 If you need evaluation samples, please place an order by August 13th, 2021.

7. Method to identify changed products

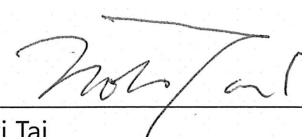
You can identify the change by the additional code that is printed on the labels.

| | Additional Code | |
|-----------------|-----------------|---------------|
| | Tray | Tape and Reel |
| Current Product | B4M or B4H | B4T or B4Q |
| Changed Product | B4A | B4S |

8. Customer response

Please acknowledge above and send your acceptance notification by September 30th, 2021.
 If we do not receive your response by the above date, we will deem this change accepted.
 If you have any inquiry of this subject, please contact our sales representatives.
 We appreciate your understanding and cooperation.

Sincerely,



 Nobuyuki Tai
 Group Manager
 Memory Customer Quality Engineering Group
 Memory Q&R Engineering Department
 KIOXIA Corporation